



Performance Characteristics of the POWER8™ Processor









Designed for Big Data - optimized for analytics performance

Processors

flexible, fast execution of analytics algorithms

Memory

large, fast workspace to maximize business insight

Data Bandwidth

bring massive amounts of information to compute resources in real-time

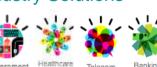
Optimized for a broad range of data and analytics:

















POWER8 Processor

Technology

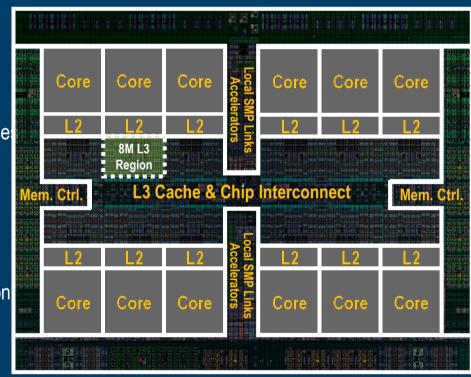
•22nm SOI, eDRAM, 15 ML 650mm2

Cores

- •12 cores (SMT8)
- •8 dispatch, 10 issue, 16 exec pipe
- •2X internal data flows/queue
- Enhanced prefetching
- •64K data cache, 32K instruction cache

Accelerators

- Crypto & memory expansion
- Transactional Memory
- VMM assist
- Data Move / VM Mobility



Energy Management

- •On-chip Power Management Micro-controller
- Integrated Per-core VRM
- Critical Path Monitors

Caches

- •512 KB SRAM L2 / core
- •96 MB eDRAM shared L3
- •Up to 128 MB eDRAM L4 (off-chip)

Memory

•Up to 230 GB/s sustained bandwidth

Bus Interfaces

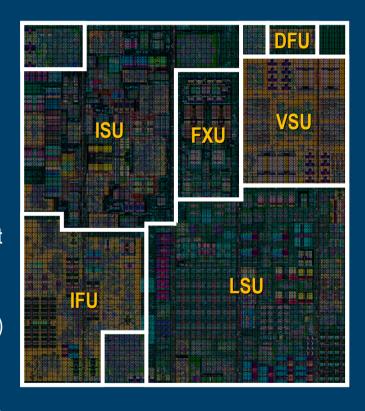
- Durable open memory attach interface
- •Integrated PCIe Gen3
- •SMP Interconnect
- •CAPI (Coherent Accelerator Processor Interface)



POWER8 Core

Execution Improvement vs. POWER7

- •SMT4 → SMT8
- •8 instruction dispatch
- •10 instruction issue
- •16 execution pipes:
 - 2 Fixed Point, 2 Ld/Store, 2 Ld
 - 4 Floating Point, 2 Vector
 - 1 Crypto, 1 Decimal Floating Point
 - 1 Conditional, 1 Branch
- •Larger Issue queues (4 x 16-entry)
- •Larger completion table (28 groups)
- •Larger Ld/Store reorder (128 / thrd)
- •Improved branch prediction
- •Improved unaligned storage access



Larger Caching Structures vs. POWER7

- •2x L1 data cache (64 KB)
- •2x outstanding data cache misses
- •4x translation Cache

Wider Load/Store

- •32B \rightarrow 64B L2 to L1 data bus
- •2x data cache to execution dataflow

Enhanced Prefetch

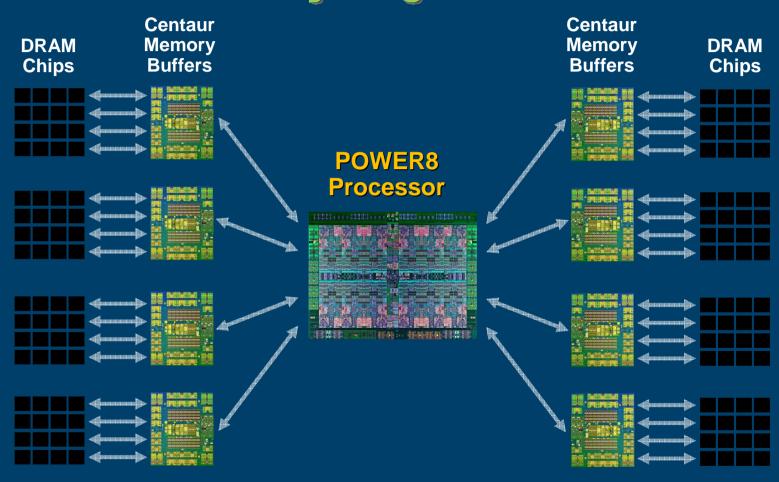
- •Instruction speculation awareness
- Data prefetch depth awareness
- •Adaptive bandwidth awareness
- Topology awareness

Core Performance vs . POWER7

~1.6x Thread ~2x Max SMT



POWER8 Memory Organization

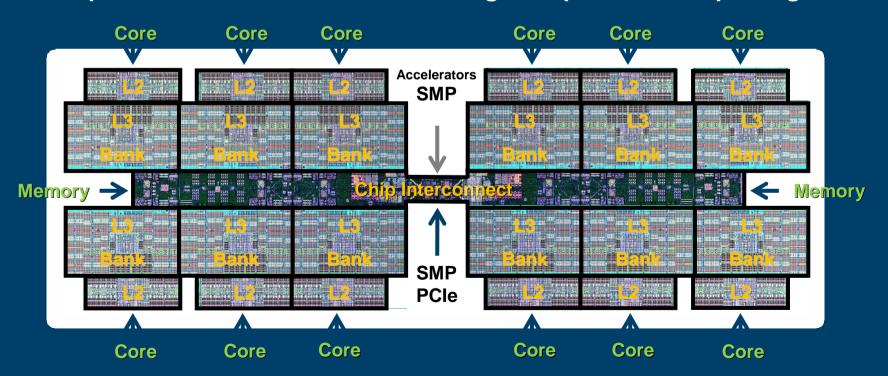


- Up to 8 high speed channels, each running up to 9.6 Gb/s for up to 230 GB/s sustained
- Up to 32 total DDR ports yielding 410 GB/s peak at the DRAM
- Up to 1 TB memory capacity per fully configured processor socket (at initial launch)



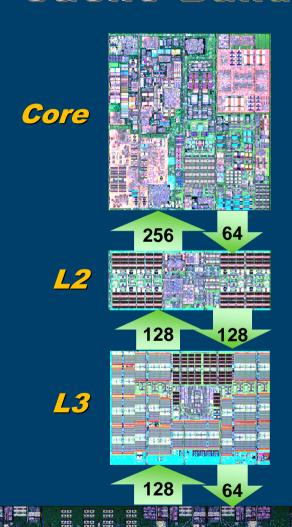
POWER8 On Chip Caches

- L2: 512 KB 8 way per core
- L3: 96 MB (12 x 8 MB 8 way Bank)
- "NUCA" Cache policy (Non-Uniform Cache Architecture)
 - Scalable bandwidth and latency
 - Migrate "hot" lines to local L2, then local L3 (replicate L2 contained footprint)
- Chip Interconnect: 150 GB/sec x 16 segment per direction per segment





Cache Bandwidths



- **⇒**GB/sec shown assuming 4 GHz
 - Product frequency will vary based on model type
- **→** Across 12 core chip
 - 4 TB/sec L2 BW
 - 3 TB/sec L3 BW





POWER8 Coherent Accelerator Processor Interface (CAPI)

Virtual Addressing

- Accelerator can work with same memory addresses that the processors use
- Pointers de-referenced same as the host application
- Removes OS & device driver overhead

Hardware Managed Cache Coherence

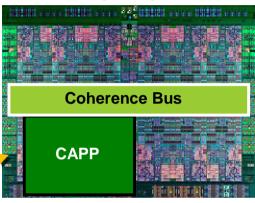
• Enables the accelerator to participate in "Locks" as a normal thread Lowers Latency over IO communication model



Customizable Hardware Application Accelerator

- •Specific system SW, middleware, or user application
- •Written to durable interface provided by PSL

POWER8



PCIe Gen 3

Transport for encapsulated messages

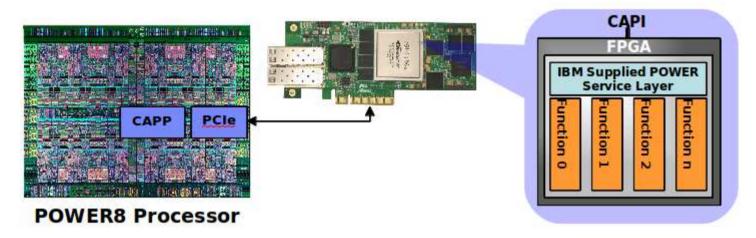
Processor Service Layer (PSL)

- Present robust, durable interfaces to applications
- Offload complexity / content from CAPP





Coherent Accelerator Processor Interface (CAPI) Flow Overview



Typical I/O Model Flow



Flow with a Coherent Model



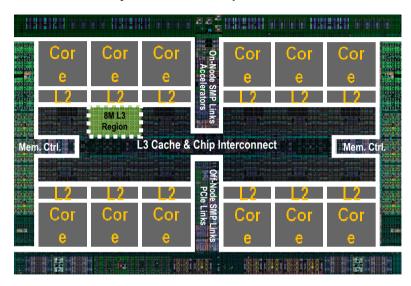


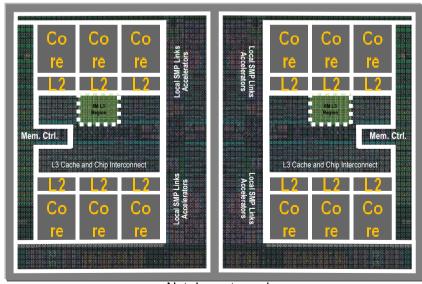


Scale-Out Processor Version (Announced April 2014)

- Scale-UP Processor (Shown at Hot Chips 25)
 - Optimized for Large SMP
 - 22nm SOI, eDRAM, 15 ML 650mm2
 - 12 Core Chip
 - 32x PCIe Gen3 (16x CAPI)
 - Large memory capacity and bandwidth

- Scale-Out Processor (1 module per socket)
 - Optimized for Scale-OUT systems
 - 2 x 6-Core Chip (362mm2 each)
 - 48x PCIe Gen3 (32x CAPI)
 - Same core, L2, L3, etc









New Power Scale-out systems built with open innovation to put data to work

Designed for Big Data



Superior Cloud Economics



Open Innovation Platform







Power S822L



Power S812L

- 1 or 2 sockets
- 10 or 12 cores/socket

















Power S824 or Power S814



Power S822

- 1 or 2 sockets
- 6, 8,10 or 12 cores/socket





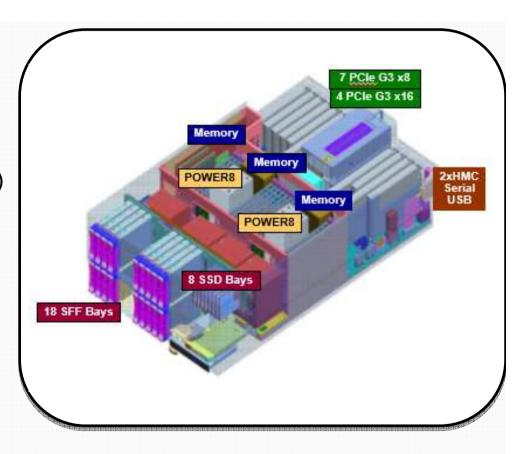






New Power Scale-out systems detailed features

- 2 Sockets (1 socket upgradeable)
- Up to 24 cores (192 threads)
- Up to 1 TB memory capacity
- Hot Plug PCle gen 3 Slots
- SR-IOV support (statement of direction)
- Ethernet: Quad 1 Gbt / (x8 slot)
- Native I/O
 - USB (3), Serial (2), HMC (2)
- Internal Storage
 - Up to 18 SFF Bays
 - Up to 8 1.8" SSD Bays (Easy Tier)
 - DVD
- Power Supplies: (200-240 AVC)







Introducing record breaking Enterprise Systems with POWER8 designed to take on the most complex data challenges

- ✓ Tackle your largest workloads with increased system scalability
- ✓ Deliver insights in real time with increased performance per-core
- ✓ Maximize your customers **experience with Enterprise** RAS

- ✓ Reduce costs with increased energy efficiency
- ✓ Manage the peaks and valleys of workloads **Power Enterprise Pools**
- ✓ Manage a wider range of workloads with up to 20 VMs per-core

Power E870

- Up to 80 cores
- 32 or 40 core nodes (5U)
- Up to 4TB Memory
- 1 or 2 Nodes per system

Power E880

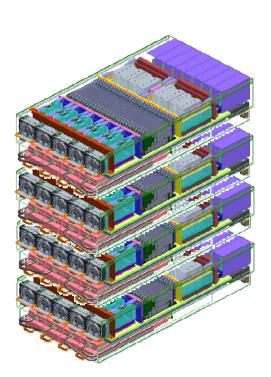
- Up to 128* cores
- 32 or 48 core nodes (5U)
- Up to 16* TB Memory
- 1 to 4 Nodes per system







Scale-Up System Design Overview



- 1 4 CEC Drawers in 2015
- 2 CEC drawers in 2014
- 4 Sockets per CEC
- ■Up to 4TB per CEC drawer memory
 - ■32 memory slots per drawer
- Eight PCIe Gen3 x16 PCIe slots in CEC drawer
 - low profile cards
- Up to 16 PCIe IO Drawers in 2015 (4/CEC drawer)
- Up to 4 PCIe I/O drawers in 2014 (2/CEC drawer)
- No SAS bays in CEC (no integrated SAS controller in CEC)
- No tape/DVD bay in CEC (no integrated controller in CEC
- No GX slots for I/O drawer attach (use PCle slots)
- No integrated multifunction card IMFC like 770/780 (need PCIe slot for any Ethernet)





POWER8 Performance Characteristics





POWER8 Performance Monitor

- Evolutionary approach
 - Incorporate experience from previous products
 - Reduces learning cycle with new hardware
 - Reduces tools requirements
- Support new hardware capability
 - SMT8
- Incremental improvements to features
 - CPI Stack
 - Event Register
 - Sampling
- Improve verification
 - VHDL Simulation
 - Virtual Bring-up
 - Early Lab testing





Concepts





Speculative Counters

- Introduced in PPC970 and POWER5
- Sometimes we don't know why we're waiting until after we're done
 - Could implement a scratch counter, dump into PMC when sure
 - Additional counters, wide adder for each PMC
- At beginning of a wait
 - Checkpoint counter value
 - Speculatively count cycles for a particular reason
- At end check reason
 - Correct: keep count
 - Incorrect: restore to checkpoint value
- Memory Latency Events
 - Speculatively count latency by data source
 - Start counting on DL1 miss
 - Rewind or commit based on actual source at cache reload time
- CPI Stack
 - Speculatively count completion stalls by reason
 - Start counting when nothing to complete AND pipeline is not empty
 - Rewind or commit based on actual stall reason once cleared
 - Last stall to clear





Sampling (Profiling)

- Continuous Sampling (every completion)
 - Group Address
 - Cache Address
 - DL1 Reload
 - ERAT Reload
 - Good for time-based or instruction count-based profiling
- Random sampling
 - Randomly mark (tag) one instruction
 - Annotate events with mark bit
 - Capture effective addresses
 - Instruction Address
 - Data Operand Address
 - Populate Event Register (introduced in POWER6)
 - Easy to implement
 - No temporal bias
 - 3rd cache miss in a burst
 - Very low overhead
 - Hard to sample rare events





CPI Stack

- At completion, looking back
 - Completing Instructions
 - Pipeline is empty (my thread had no instructions in the pipe)

Icache miss

Branch mispredict

Other?

- Stalled

Load/Store

- Dcache miss
- Translation miss
- Reject
- Other

Fixed Point

Floating Point

Branch

Other?





POWER7 CPI Stack What was the last condition that delayed completion?

	Completion Stall Cycles	Stall by FXU	FXU Multi-Cycle Instruction		
			FXU Other		
		Stall by FPU	FPU Divide/SQRT		
			FPU Other		
		Stall by VMX	VMX Long		
			VMX Other		
		Stall by LSU		Translation Stall	
			Stall by Reject	Other Reject	
Cycles			Stall by D-Cache Miss		
<u>C</u>			LSU Other		
Ň		Other Stall			
	GCT Empty Cycles	GCT Empty due to Icache Miss			
		GCT Empty due to Branch Mispredict			
		GCT Empty due to Icache Miss + Branch Mispredict			
		GCT Empty other			
	Completion Cycles (Group Completed)				





POWER8 Performance Monitor Enhancements

- Sampling enhancements
 - Added random event sampling
 - Expanded Event Register for sampled instructions
 - Sample Filtering
 - "Needle in haystack" problem
 - Reduces number of samples presented to software by filtering out uninteresting ones
- Hotness table
 - Hardware keeps track of recently sampled addresses and generates an interrupt if the address is "hot"
- Branch History Rolling Buffer
 - Rolling list of recent branches
 - Can be used to detect branch prediction problems
 - Can be used as a call trace leading up to Performance Monitor interrupt
- Event-Based Branches (User Mode Interrupts)
 - Allows user-mode programs to catch Performance Monitor alerts
 - Reduces overhead for user-mode programs to monitor themselves



POWER8 CPI Stack



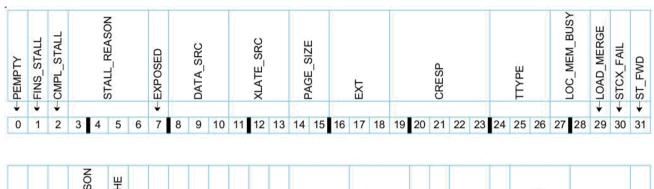
- Introduced with PowerPC970, the CPI stack uniquely identifies components of CPI (Cycles Per Instruction)
- Enhanced every generation to add detail and eliminate "other" category
- POWER8 splits dependency chains within a group to separate cause and effect (e.g. long latency load feeding 1 cycle add)
- Items in blue are new with POWER8

			Stall due to Branch			
		Stall due to BR or CR	Stall due to CR			
			Stall due to CR Stall due to Fixed-Point long			
		Stall due to Fixed Point				
			Stall due to Fixed-Point (other)			
	Stalled Cycles		Stall due to Vector	Stall due to Vector long		
		Stall due to Vector/Scalar		Stall due to Vector (other)		
			Stall due to Scalar	Stall due to Scalar long		
			Stall due to Scalar (other)			
			Stall due to Vector/Scalar (other)			
				Stall due to L2/L3 Hit	L2/L3 hit with conflict	
					L2/L3 hit with no conflict	
	<u> </u>				Stall due to On-chip L2/L3	
	<u> </u>		Stall due to Dcache Miss	C4-II d 4- 1 2 Mi	Stall due to On-chip Memory	
	Ω			Stall due to L3 Miss	Stall due to Off-chip L2/L3	
	<u>ĉ</u>				Stall due to Off-chip Memory	
	0	01-11-1		D-14-14-1-	Stall due to Off-node Memory	
	, o,	Stall due to Load/Store		Reject due to Load-Hit		
			Stall due to LSU Reject	Reject due to ERAT Miss		
				Reject due to LMQ Full		
			Reject due to Reject (other)			
Cycles			Stall due to Store Finish			
Ċ			Stall due to Load Finish			
0			Stall due to Store Forward			
0)		Stall due to Load/Store (other)				
		Stall due to Next-To-Complete Flush				
	Waiting to Complete	Stall Cycles (other)				
	Waiting to Complete	Blocked due to LWSYNC				
		Blocked due to HWSYNC				
	Thread Blocked	Blocked due to ECC Delay				
		Blocked due to Flush				
		Blocked due to COQ Full Throad Blocked (Other)				
		Thread Blocked (Other) Completion Table Fronts due to Locabe L2 Mice				
		Completion Table Empty due to lcache Miss	Completion Table Empty due to Icache L3 Miss			
			Completion Table Empty due to Icache Miss (Other)			
		Completion Table Empty due to Branch Mispredict				
	Completion Table Empty	Completion Table Empty due to Branch Mispredict + Icache Miss				
	Completion Table Empty	Completion Table Empty - Dispatch Held	Dispatch Held due to Mapper Dispatch Held due to Store Queue			
			Dispatch Held due to Issue Queue			
		Dispatch Held (Other) Completion Table Empty (Other)				
	Othor	Completion Table Empty (Other)				
	Other					
	Completion Cycles					





Sampled Instruction Event Register (SIER)





- Augments sampling-based performance analysis and profiling
- Detailed information is collected for sampled instruction
 - Instruction type
 - CPI Stack
 - Branch prediction
 - Cache access
 - Translation

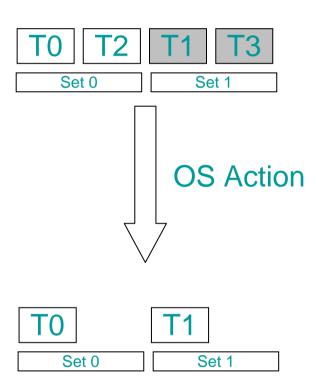




POWER7 SMT Design



- Divided into two thread sets
 - Static mapping between thread number and thread set
 - Moving to lower SMT level requires
 Move execution to appropriate thread(s)
 Nap remaining thread(s)
 Request SMT level change
 - OS tries to keep threads balanced between thread sets by moving execution to appropriate thread





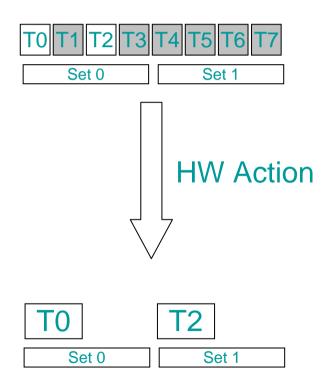


POWER8 SMT Design

POWER8 automatically tunes itself



- Divided into two thread sets
 - Dynamic mapping between thread number and thread set
 - Moving to lower SMT level requires
 Nap the idle thread
 Hardware will shift to the appropriate
 SMT level
 - Hardware monitors active threads and balances threads between the thread sets







POWER8 Vector/Scalar Unit (VSU)

	POWER7	POWER8
Base SIMD	1X Simple 1X Permute 1X Complex W/DW aligned support	2X Simple (FX and Logical) 2X Permute (byte shuffling manipulation) 2X Complex (integer multiplication) Byte aligned support
Integer SIMD	32 bit integer	64 bit integer 128 bit integer extension/bit permute
Compression /Unstructured data/Parallel Bit Stream Processing	-	On-Chip Accelerator Vector CLZ, Vector Gather bits GR-VR Direct Move
Crypto	-	On-Chip Accelerator AES/SHA User level instructions
RAID CRC/syndrome (Check sum calculation)	-	Vector Polynomial Multiply
Binary Floating Point	8 DP Flops/cyc 8 SP Flops/cyc	8 DP Flops/cyc 16 SP Flops/cyc
Decimal	Non-Pipelined	Pipeline





Hardware Encryption

- On-Chip Hardware Accelerators introduced with POWER7+
 - POWER8 has same accelerators
 - Offload encryption for OS-based large messages (encrypted file systems, etc)
- POWER8 includes user-mode instructions to accelerate common algorithms

Algorithm	POWER7+	POWER8	
Algorithm	On-Chip	On-Chip	In-Core
AES-GCM	✓	✓	✓
AES-CTR	✓	✓	✓
AES-CBC	✓	✓	✓
AES-ECB	✓	✓	✓
SHA-256	✓	✓	✓
SHA-512	✓	✓	✓
RNG	✓	✓	
CRC			✓

Cycles per Byte

A loro vitlo vo	POWER7[+]	POWER8 (HW)	
Algorithm	(SW)	Single Thread	Multi Thread
SHA512	35	10.7	2.6
AES-128-ENC	17	4	0.8
AES-256-ENC	21	5.5	1.1

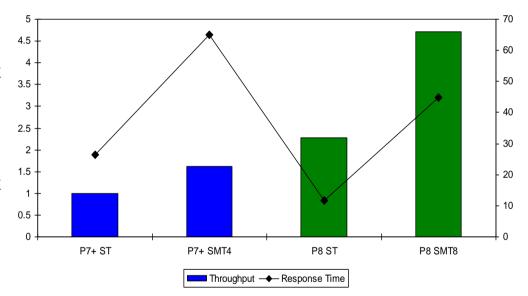




POWER8 Batch Performance

POWER8 Reduces Batch Window Requirements

- 56% lower response time and 2.3x more throughput with POWER8 (Single Thread mode) than POWER7+ (Single Thread Mode)
- 82% lower response time and 1.4x more throughput with POWER8 (Single Thread mode) than POWER7+ (SMT4)
- 31% lower response time and 2.9x more throughput with POWER8 (SMT8) than POWER7+ (SMT4)



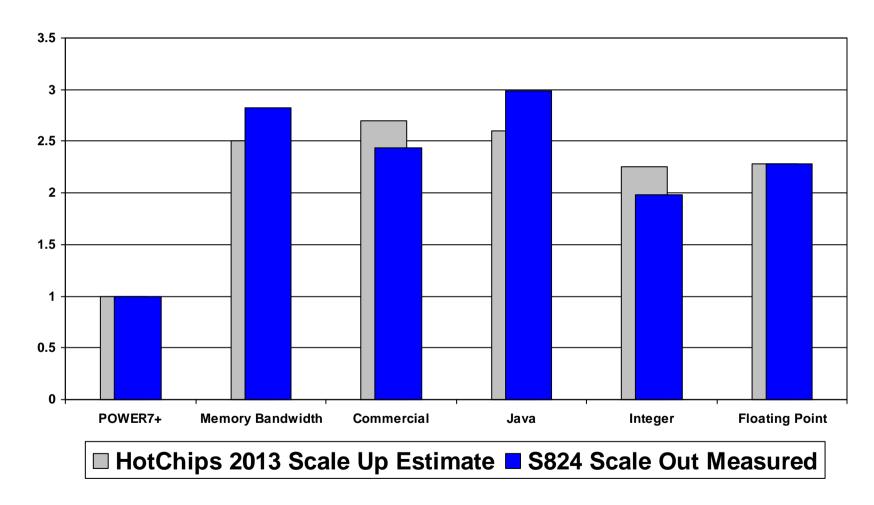
POWER8 vs. POWER7+ processor performance on an IBM internal workload that emulates batch tasks performing compression where response time is important.

POWER7+ 740 - 16C POWER8 S824 - 16C





POWER8 Socket Performance



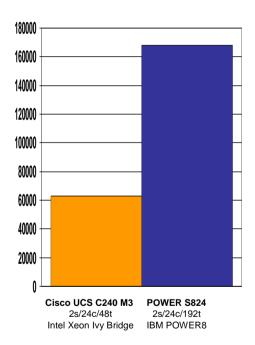
POWER7+ 740 - 16C POWER8 S824 - 24C



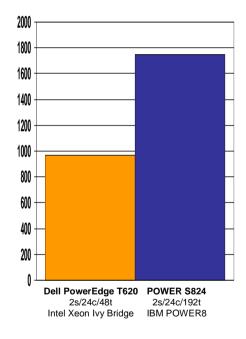


Up to 2.7x performance across key workloads vs. other 24-core Scale-Out Systems

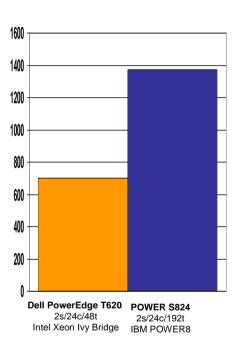
Java - SPECjbb2013 (Max-jOPS) 2.7x Performance



SPECint rate2006 1.8x Performance



SPECfp rate2006 2x Performance



Results are based on best published results on Xeon E5-2697 v2 from the top 5 Intel system vendors.

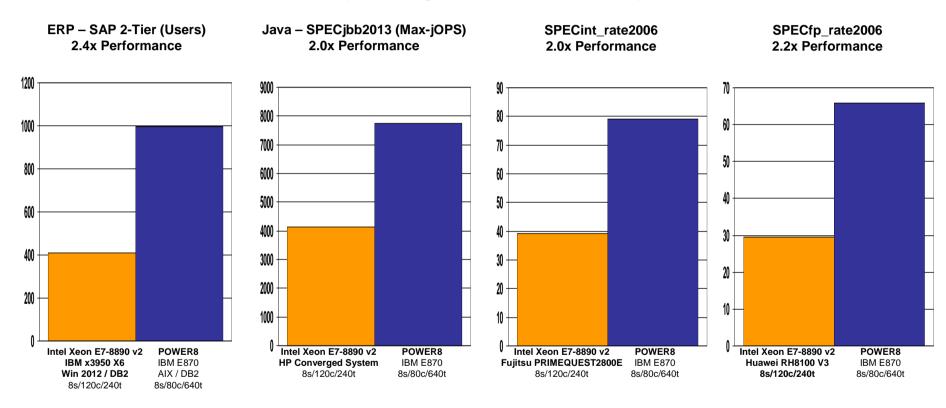
SPECjbb2013 results are valid as of 7/7/2014. For more information go to http://www.specbench.org/jbb2013/results

²⁾ SPECcpu2006 results are submitted as of 4/22/2014. For more information go to http://www.specbench.org/cpu2006/results/





2x to 2.4x core performance advantage with E870 versus 8-socket x86 lvy Bridge-EX across key workloads



- Results are based on best published per core results on Xeon E7-8890 processor.
- SAP results are based on the two-tier SAP SD standard application benchmark running SAP enhancement package 5 for the SAP ERP 6.0 application. Results valid as of October 3, 2014. IBM Power Enterprise System E870 on the two-tier SAP SD standard application benchmark running SAP enhancement package 5 for the SAP ERP 6.0 application; 8 processors / 80 cores / 640 threads, POWER8; 4.19GHz, 2048 GB memory, 79,750 SD benchmark users running AIX® 7.1 and DB2® 10.5, Certification #: 2014034 Result valid as of October 3, 2014. Source: http://www.sap.com/benchmark. IBM System x3950 X6 on the two-tier SAP SD standard application benchmark running SAP enhancement package 5 for the SAP ERP 6.0 application; 8 processors / 120 cores/ 240 threads, Intel Xeon Processor 8890 v2; 2.80 GHz, 1024 GB memory; 49,000 SD benchmark users, running Windows Server 2012 Standard Edition and DB2 10: Certification # 2014024. Source: http://www.sap.com/benchmark.
- SPECjbb2013 results are valid as of 10/2/2014. For more information go to http://www.specbench.org/jbb2013/results/ All IBM benchmark results will be submitted to spec.org on October 6, 2014.
- SPECcpu2006 results are submitted as of 10/2/2014. For more information go to http://www.specbench.org/cpu2006/results/ All IBM benchmark results will be submitted to spec.org on October 6, 2014.







Designed for Big Data - optimized for analytics performance

Processors

flexible, fast execution of analytics algorithms

Memory

large, fast workspace to maximize business insight

Data Bandwidth

bring massive amounts of information to compute resources in real-time

Optimized for a broad range of data and analytics:

























Thank You!











Definitions

- eDRAM = embedded DRAM
- SMP = Simultaneous Multi-Processing
- SMT = Simultaneous Multi-Threading
- SR-IOV = Single Root I/O Virtualization
- HMC = Hardware Management Console
- SFF = Small Form Factor





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